

Product Change Notification - JAON-23UZTC781

Date:

04 Jun 2019

Product Category:

32-bit Microcontrollers; Touchscreen Controllers

Affected CPNs:

7

Notification subject:

CCB 3130 Final Notice: Qualification of ASCL as an additional bumping facility for selected Atmel products available in 20L, 35L, 36L, 45L, 49L and 64L WLSCP package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASCL as an additional bumping facility for selected Atmel products available in 20L, 35L, 36L, 45L, 49L and 64L WLSCP package.

Pre Change:

Bumping facility at ASEK site.

Post Change:

Bumping facility at ASEK or ASCL site.

Pre and Post Change Summary:

	Pre Change	Post Change						
Bumping facility /	ASE Inc. (ASEK)	ASE Inc. (ASEK)	ASE Group Chung-Li					
Assembly Site	AGE IIIC. (AGER)	AGE IIIC. (AGER)	(ASCL)					
RDL material	Ti/Al/Ti	Ti/Al/Ti	Ti/Al/Ti					
UBM composition	Al/NiV/Cu	Al/NiV/Cu	Al/NiV/Cu					
PBO material	HD8820	HD8820	HD8820					

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve cycle time by qualifying ASCL as an additional bumping facility.

Change Implementation Status:

In Progress

Estimated First Ship Date

July 5, 2019 (date code: 1927)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2017			->	June 2019				July 2019					
Workweek	44	45	46	47		23	24	25	26	27	28	29	30	31



Initial PCN Issue Date		Х					
Qual Report Availability			Х				
Final PCN Issue Date			Х				
Estimated					V		
Implementation Date					^		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

November 24, 2017: Issued initial notification.

June 4, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on July 5, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-23UZTC781_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section. If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. JAON-23UZTC781 - CCB 3130 Final Notice: Qualification of ASCL as an additional bumping facility for selected Atmel products available in 20L, 35L, 36L, 45L, 49L and 64L WLSCP package.

Affected Catalog Part Numbers (CPN)

ATMXT144U-UUR028 ATSAMD10D14A-UUT ATSAMD10D14A-UUTB5 ATSAMD10D14A-UUTBN ATSAMD11D14A-UUT ATSAMD20G17A-UUT ATSAMD20G18A-UNT ATSAMD20G18A-UUT ATSAMD21E15C-UUT ATSAMD21E16C-UUT ATSAMD21E16C-UUTB4 ATSAML21J17B-UUT ATSAML21J18B-UUT ATSAML22G17A-UUT ATSAML22G17A-UUTA0 ATSAML22G17A-UUTA1 ATSAML22G17A-UUTA2 ATSAML22G18A-UUT NI32D14-UUTBN